



BROADPAK JOINS SOI INDUSTRY CONSORTIUM

SOI Ecosystem Expands to Include Advanced Packaging Development

Boston, MASS., May 6, 2010 – The [SOI Industry Consortium](#), aimed at accelerating silicon-on-insulator (SOI) innovation across broad markets, announced today that [BroadPak](#) has joined the worldwide organization. BroadPak is a premier provider of semiconductor package design and development services. The addition of BroadPak, with its unique silicon-package co-design methodology, expands opportunities for SOI chip developers to reduce product cost and improve chip and system performance without impacting chip development schedules.

“BroadPak brings its expertise in advanced high-performance, high pin-count package design and test to the SOI community,” said Farhang Yazdani, president and chief technical officer of Broadpack. “We look forward to collaborative relationships with other members of the SOI Industry Consortium to meet the demands of the highly integrated, high performance and low voltage systems that are made possible with SOI.”

“We are extremely pleased to have BroadPak join us,” said Horacio Mendez, executive director of the SOI Industry Consortium. “As a leading supplier of advanced packaging design services, BroadPak brings valuable and complementary expertise to our ecosystem of companies and assembly-level enablement in this time of SOI market acceleration.”

The SOI Industry Consortium welcomes companies, organizations, government and academic institutions to join the group in extending Moore’s law scaling and applying the full benefits of SOI-based electronics to global sustainability challenges, lowering the total cost-of-ownership of electronics and improving the quality of life.

About the SOI Industry Consortium:

The SOI Industry Consortium is chartered with accelerating silicon-on-insulator (SOI) innovation into broad markets by promoting the benefits of SOI technology and reducing the barriers to adoption. Providing a platform for global collaboration throughout the value chain, the SOI Industry Consortium's membership includes: ARM, BroadPak, Cadence Design Systems, CEA-Léti, Freescale Semiconductor, GLOBALFOUNDRIES, IBM, IMEC, Infotech, Innovative Silicon, Kanazawa Institute of Technology, KLA-Tencor, MEMC, Mentor Graphics, MIT Lincoln Laboratories, Nvidia, Ritsumeikan University, Samsung, Semico, SEH Europe, Soitec, Stanford University, STMicroelectronics, Synopsys, Tyndall Institute, University of California-Berkeley, University Catholique de Louvain, UMC and Varian. Membership is open to all companies and institutions throughout the electronics industry. For more information please visit www.soiconsortium.org.

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